

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

July 17, 2003

Hideo KOBAYASHI, Shinichi SHINOHARA, Hironobu NISHIMURA, and Yukio UTSUNOMIYA

For : METHOD AND APPARATUS FOR CURING ADHESIVE
BETWEEN SUBSTRATES, AND DISK SUBSTRATES BONDING
APPARATUS

Our Docket : SHX 340

Mail Stop: Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313

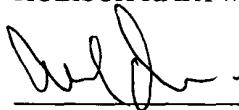
Sir:

CLAIM OF FOREIGN PRIORITY

Applicants hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below.

1. Japanese Patent Application Number: 2002-209897.
Filed with the Japanese Patent Office on: July 18, 2002.
2. Japanese Patent Application Number: 2002-307283.
Filed with the Japanese Patent Office on: October 22, 2002.
3. Japanese Patent Application Number: 2002-307385.
Filed with the Japanese Patent Office on: October 22, 2002.
4. Japanese Patent Application Number: 2003-188734.
Filed with the Japanese Patent Office on: June 30, 2003.

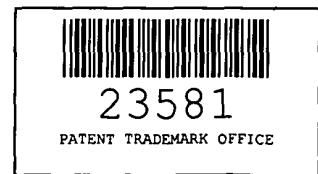
Respectfully submitted,
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Date of Mailing



MDA:gp
Enclosures